

ABSTRACT

SEMICONDUCTOR PACKAGE AND METOHD OF MANUFACTURING

SEMICONDUCTOR PACKAGE

A semiconductor package includes a substrate having a first surface, a second surface opposite the first surface, and interconnect patterns disposed therein, a semiconductor device mounted on the first surface of the substrate, a layer of sealing resin sealing the semiconductor device, a plurality of external connection electrodes formed on the second surface of the substrate, an electromagnetic wave shield film for blocking electromagnetic waves, which is formed on an upper surface of the layer of sealing resin and side surfaces of the layer of sealing resin and the substrate, and a ground interconnect formed on the substrate and electrically connected to the electromagnetic wave shield film.

(Figure 7A)